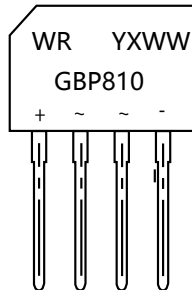


Ultrasoft Recovery Bridge



PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

Features

- Glass Passivated Chip Junction
- Reverse Voltage - 1000 V
- Forward Current - 8.0 A
- High Surge Current Capability
- Designed For Surface Mount Application

Benefits

- Case: D3K
- Terminals: Solderable Per MIL-STD-750

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

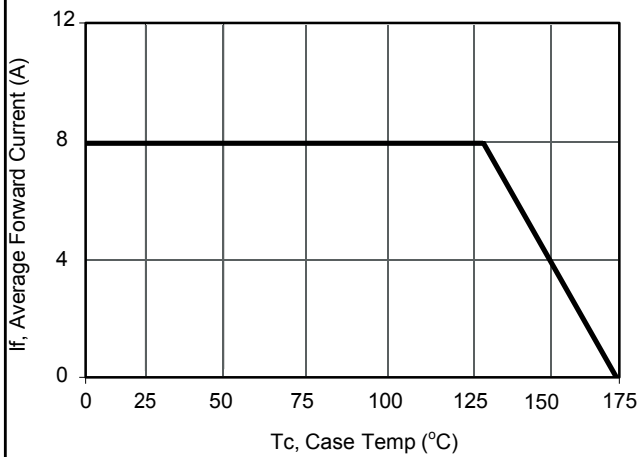
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	WRGBP810	Units
Maximum Repetitive Peak Reverse Voltage	VRRM	1000	V
Maximum RMS voltage	VRMS	700	V
Maximum DC Blocking Voltage	VDC	1000	V
Average Rectified Output Current	I_o	8.0	A
Reverse Recovery Time. $I_F=0.5A, I_R=1A, I_{RR}=0.25A$	T_{rr}	10	us
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	180	A
$I^2 t$ rating for fusing ($1ms < t < 10ms$)	$I^2 t$	93	A ² S
Maximum Forward Voltage at 4.0 A	V_F	1.0	V
Maximum DC Reverse Current @ $T_A=25\text{ }^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_A=125\text{ }^\circ\text{C}$	I_R	5 100	μA
Typical Junction Capacitance (Note1)	C_j	50	pF
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +175	$^\circ\text{C}$

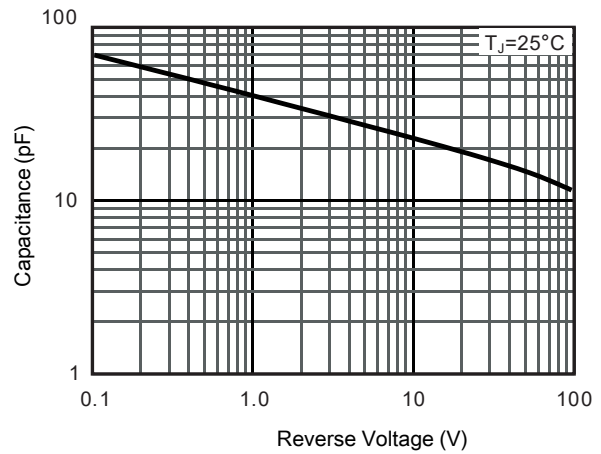
Note: 1. Measured at 1MHz and applied reverse voltage of 4 VDC.

2. Mounted on glass epoxy PC board with $4 \times 1.5" \times 1.5"$ (3.81×3.81 cm) copper pad.

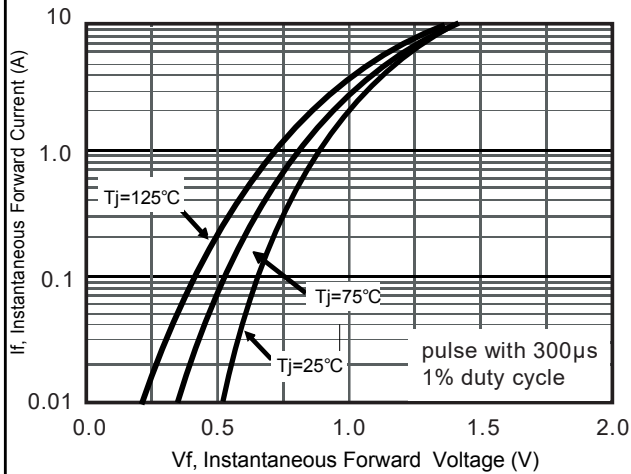
RATINGS AND CHARACTERISTICS CURVES (TA = 25 °C unless otherwise noted)



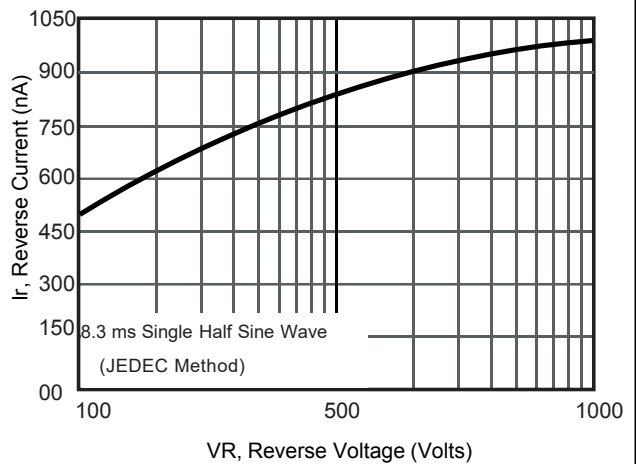
Current Derating, Case



Typical Junction Capacitance

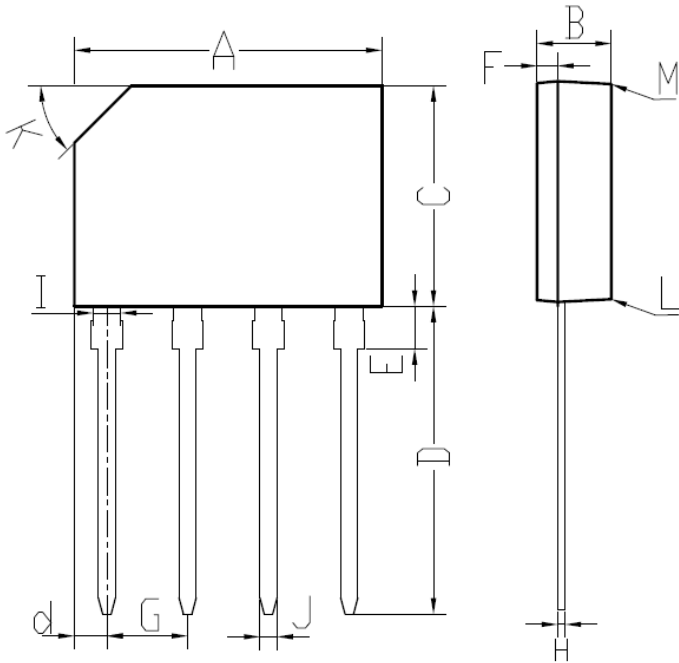


Typical Forward Voltage



Typical Reverse Current

PACKAGE OUTLINE DIMENSIONS



GBP		
DIM.	MIN.	MAX.
A	14.20	14.70
B	3.30	3.60
C	10.20	10.60
D	13.80	14.40
d	1.40	1.70
E	1.80	2.20
F	0.80	1.10
G	3.71	3.91
H	0.30	0.55
I	1.22	1.42
J	0.76	0.86
K	2.7 x 45° (Typ)	
L	#	3°
M	#	2°
All Dimensions in millimeter		